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# Non-Silicone thermally conductive putty

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GCS-NSP15 is a non silicone putty

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## Features

- High compressibility
- Non-curing
- Pump out resistant
- Long term stability
- Electrical insulation
- Low/NO siloxanes, Siloxane Volatiles D4~D20 0%



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Part number	Package
GCS-NSP15-100ml	100ml syringe

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## Applications

### Displays, lighting protection

PDP TV, LCD CCFL and LCD LED display backlight, LED signage, projectors and new display technology.

### Consumer and industrial electronics

Mobile telephone, communication base station, laptop, notebook, computer servers, handheld gaming devices, memory modules, CPU modules, amplifiers, batteries, and DC to DC convertors power supplies.

### Automotive electronics

Engine management, electronic suspension, braking systems, communication and multimedia systems, comfort convenience features, vehicle lighting, vehicle controls, hybrid vehicle battery thermal management, electric vehicle thermal management.



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## Non-Silicone thermally conductive putty

Characteristic	Test Method	Value
Colour	Visual	Dark Grey
Thickness mm	-	0.5 - 2.0
Density g/cm <sup>3</sup>	ASTM D792	2.6
Flow rate, (30cc EFD cartridge, 0.1", 90 psi) g/cm <sup>3</sup>	-	7
Application temperature °C	-	-30 - +150
BLT Thickness low limit, mm	ASTM D374	0.05
<b>Electrical</b>		
Dielectric breakdown kV/mm	ASTM D419	>10
Dielectroc constant	ASTM D150	6
Volume resistivity Ohm-m	ASTM D257	>10 <sup>13</sup>
<b>Thermal</b>		
Thermal conductivity W/m*K	ASTM D5470	1.4
Coefficient of Thermal Expansion, ppm/K	-	210

